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Lowest cost per Amp for a Modular & High Fidelity broadband DPS

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AEM



Virtual • October 27-29, 2020



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- Requirements for Unified DUT Power Supply solution
- AEM's Approach To address The Technical Challenges at affordable cost
- Summary & Closing



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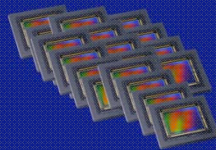
Abstract

- “The wide spectrum of SOC and SiP devices are driving a large range of DUT power supply requirements. Power supply requirements range from low power less than 1 Watt per device with up to 5 different voltages to high end GPU/Processors with switching requirements from 10 Watts to more than 300 Watts within a few microseconds.
- Mu-Test, an AEM company, is addressing these challenges by developing a unique Power supply module that covers low power/high accuracy and high power/high accuracy device needs while maintaining the required signal fidelity at an affordable cost.”

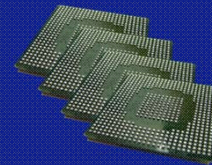
Needs for Unified DUT Power supply solution



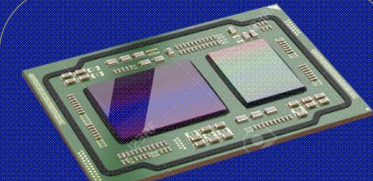
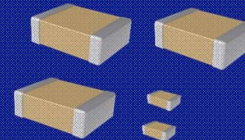
*Linear,
industrial,
automotive*



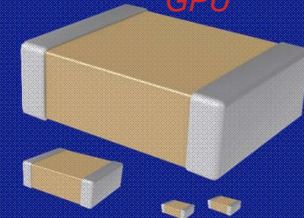
Sensors



Microcontrollers

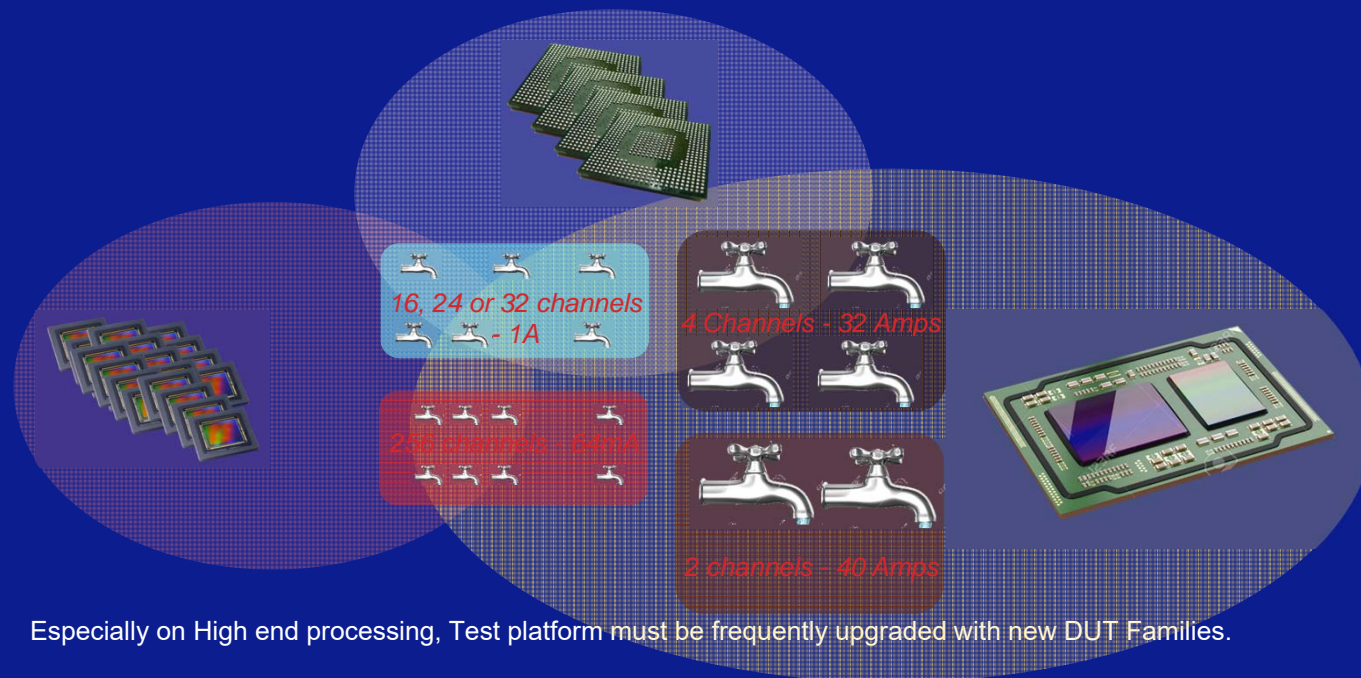


*Processors, Datacom,
GPU*



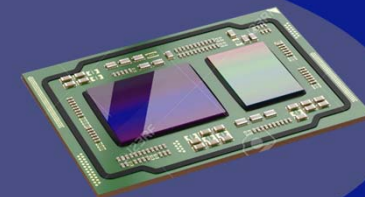
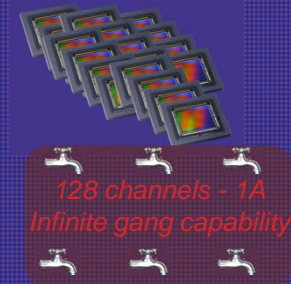
The wide spectrum of SOC and SiP devices are driving a large range of DUT power supply requirements. Power supply requirements range from low power less than 1 Watt per device with up to 5 different voltages to high end GPU/Processors with switching requirements from 10 Watts to more than 300 Watts within a few microseconds.

Needs for Unified DUT Power supply solution *Current Market DPS offering*



Needs for Unified DUT Power supply solution

AEM DPS broadband DPS offering



Needs for Unified DUT Power supply solution

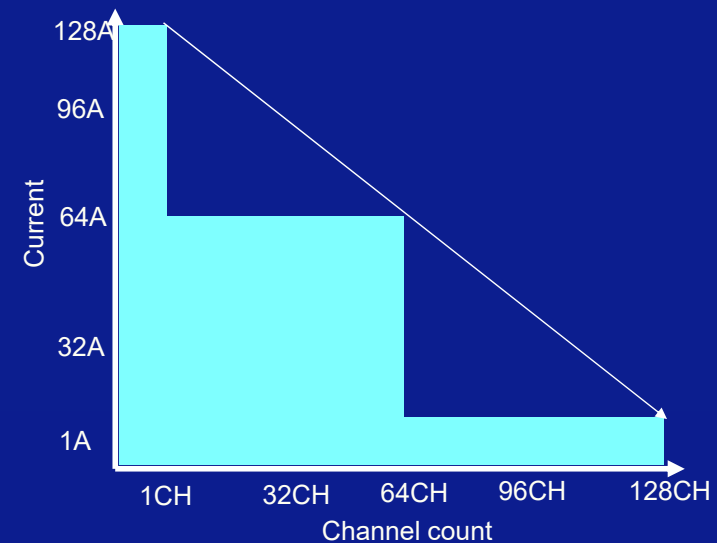
Price usage and customer expectation

Customer expectation

- In mid to low end SOC platforms, DPS cost is embedded in the platform cost structure.
- AC performance requirements for High current normally drive expensive DPS options.

Flexible Usage

- Cost per channel for ganging < 32 Amps
- Cost per A when ganging > 128A
- Cost per instrument same irrespective of power
- Gang up to 3 instruments for 3* flexibility



Unified DPS specification objectives

Sales and Market expectation

A single instrument covering:

- SOC's,
- sensors,
- High End processing (data, images, computing)

Reduce Known Good Product cost through

- Improved integration
- Unique Amplifier design covering all requirements through flexibility
- Design for high reliability

A single instrument provided with the added requirement of all DUT categories

- 128 DPS channels, 1 A each
- Voltage from -2V to 6.5 V, 9 current ranges: 5uA to 1000mA
- Max total current 128A per instrument
- Inter-instrument ganging capability (objectives: 512 A)
- 4 quadrant operation mode
- 16/18 bits DAC/ADC
- Gang mode: 2 to 128 channels
- Gang max 3 boards, max current 384A
- Programmable Current/Voltage Clamps
- Programmable slew rate
- Dual PSRR test noise injection option
- Histogram mode per channel
- Isolation/Enable per channel



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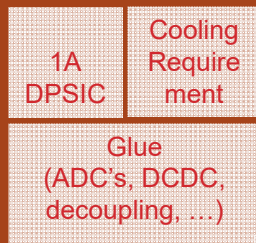
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Technical Challenges to meet specification objectives

Device Layout, modularity analysis

Theoretical Max instrument capability:
270 Cells, 270 Amps

Basic 1 Amp Cell: 600mm²



Instrument available space: 160 000mm²

Manufacturing constrains:

- First Pass Yield = F(# of DPS Cell)
- # of max LGA/BGA device change per electronic assembly
- Tradeoff between # of module type and integration/repair simplicity

Cost constrains:

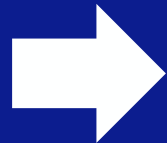
- Unique and large PCB is unaffordable
- Cost = F(# modules, connectors)

Inventory constrains:

- Minimize item value in Stock
- Minimize spare board stock value world-wide

Engineering Constrains:

- Characterization effort = F(# of channel/module)
- NRE cost = F(# module type)
- Reliability = F(θ_{jc})



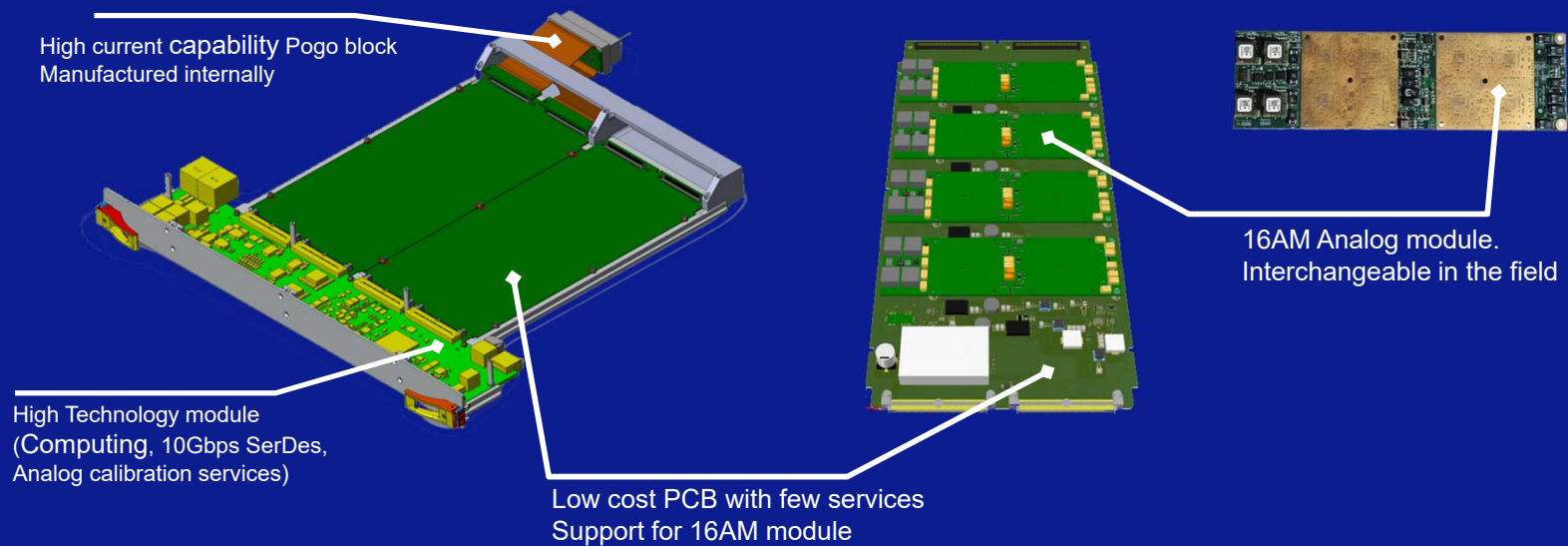
Limiting to 128 Amps/Instrument

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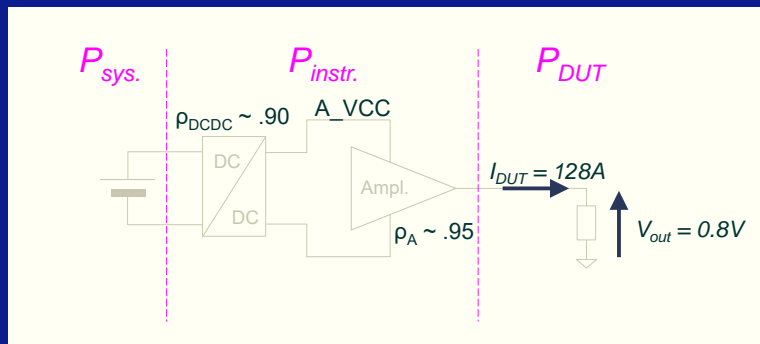
Technical Challenges to meet specification objectives

Device Layout modularity analysis



Technical Challenges

Power yield & cooling analysis



Worst case is Low voltage on DUT, eg 0.8V for processor core. With $A_VCC = 8V$

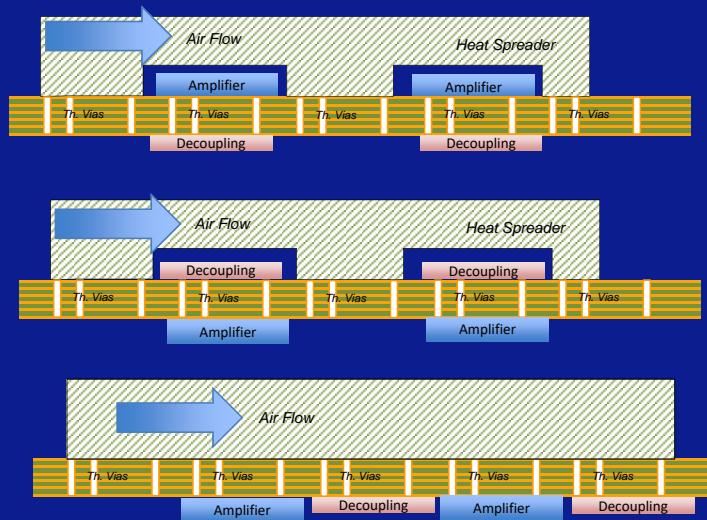
- $P_{DUT} \sim 100W$
 - $P_{ampl.} \sim 970W$, eg 7.6W per amplifier
 - $P_{sys.} \sim 1200W$ $\rho \sim 8.5\%$
- Standard linear implementation makes no longer sense

Mixed PWM / LDO design implementation significantly improves those figures

- $P_{DUT} \sim 100W$
- $P_{ampl.} \sim 300W$, eg 2.3W per amplifier
- $P_{sys.} \sim 450W$ $\rho \sim 23\%$

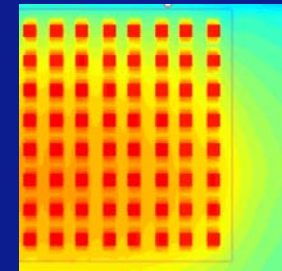
Technical Challenges to meet specification objectives

Power yield & cooling analysis



Many different configurations are simulated in order to predict the junction temperature. The parameters are mainly:

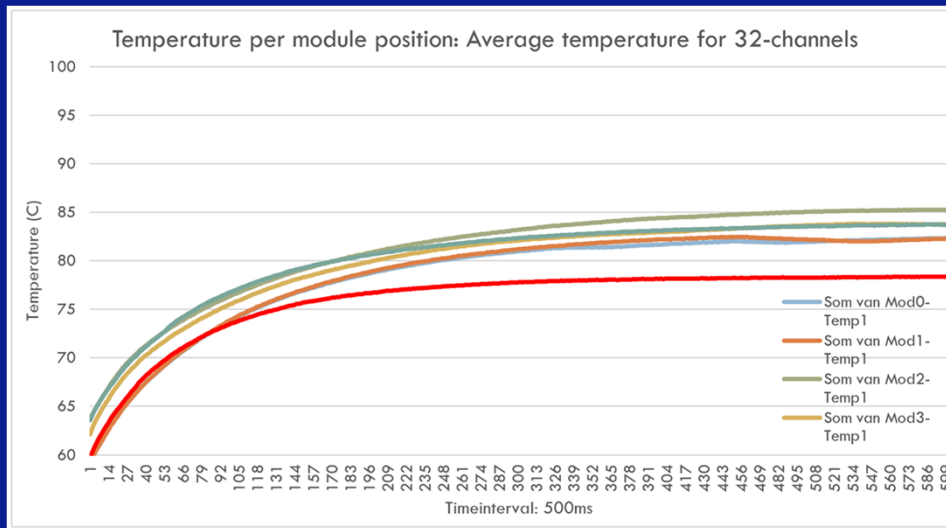
- Number of thermal via's
- Type of thermal pad
- Via fill ?
- Heat spreader design, air speed
- Number of heat conduction layers



Among the few acceptable solution's, the pcb cos and assembly process was the key decision maker

Technical Challenges to meet specification objectives

Power yield & cooling analysis



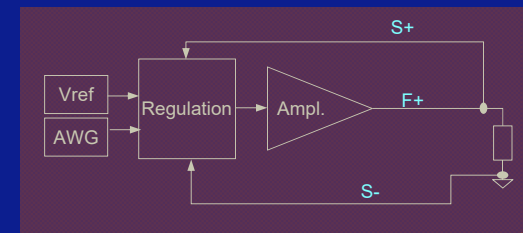
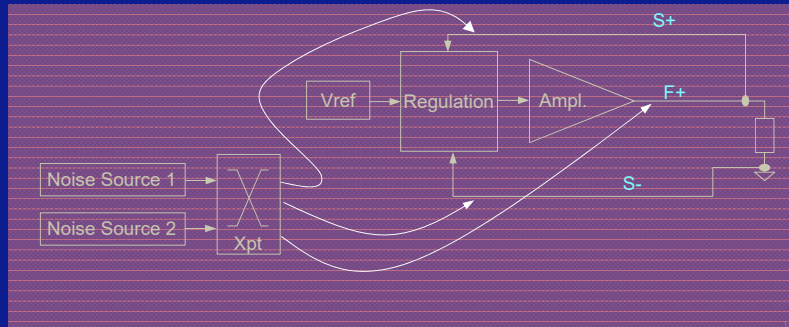
With 2 * 16AM modules in worst-case scenario configuration, the results on the Hardware are showing better than expected Junction Temperature

- Target max junction temperature 100°C
- Simulated: 90°C
- Verified: 85°C

Technical Challenges to meet specification objectives

Power Supply Rejection Ratio

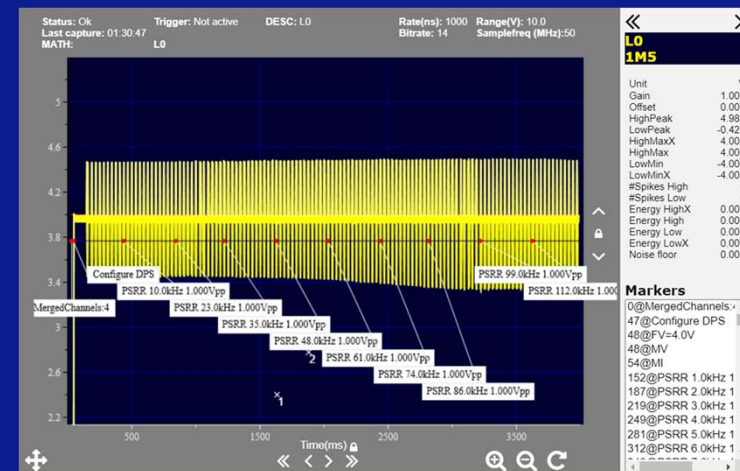
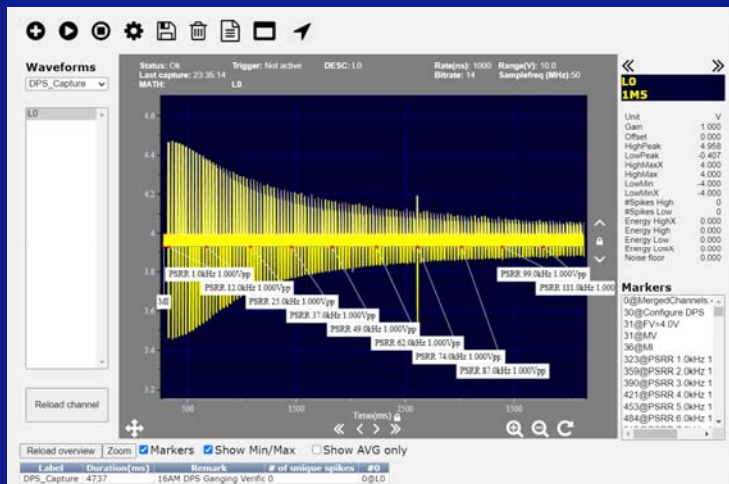
- Noise source option
 1. Independent source with switch matrix
 2. Per channel source
- Noise injection options
 1. SP coupling
 2. SM coupling
 3. F+ coupling



Technical Challenges to meet specification objectives

Power Supply Rejection Ratio

Retained solution is improvement of the Voltage reference transformed into AWG, characterize the path and proceed with correction table $G=F(\text{Freq})$

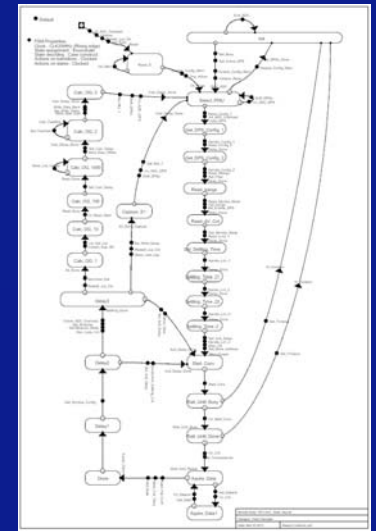
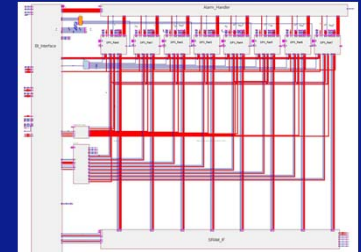


Technical Challenges to meet specification objectives

Parallel efficiency

Requirements for parallel processing

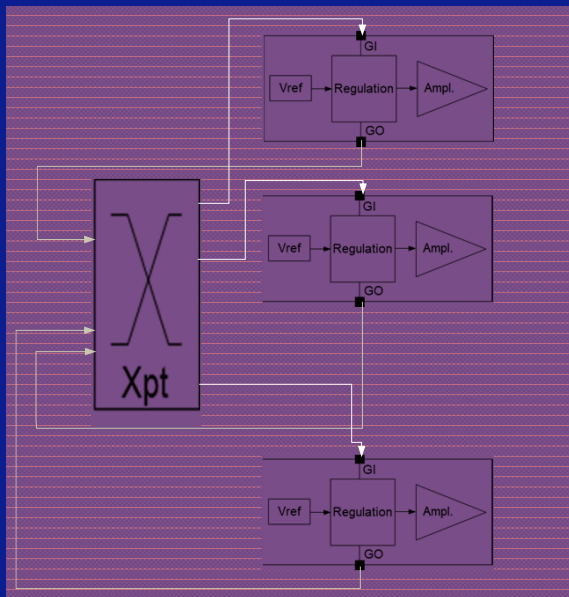
- No microcontroller on hardware
- Use FPGA with replicated State parallel state machine
- The FPGA's on HDPS128 performs many functions normally done in software:
- Forcing values, range settings, protection
- Measuring values, averaging
- Calibration, single/multi segment, range dependent
- Result processing pass/fail limit checks
- Tempco guarding/adjustments
- Failing DUT handling
- Each done in full parallel per DPS on one board and synced with multiple boards



Technical Challenges to meet specification objectives

Gang capability

Original Design

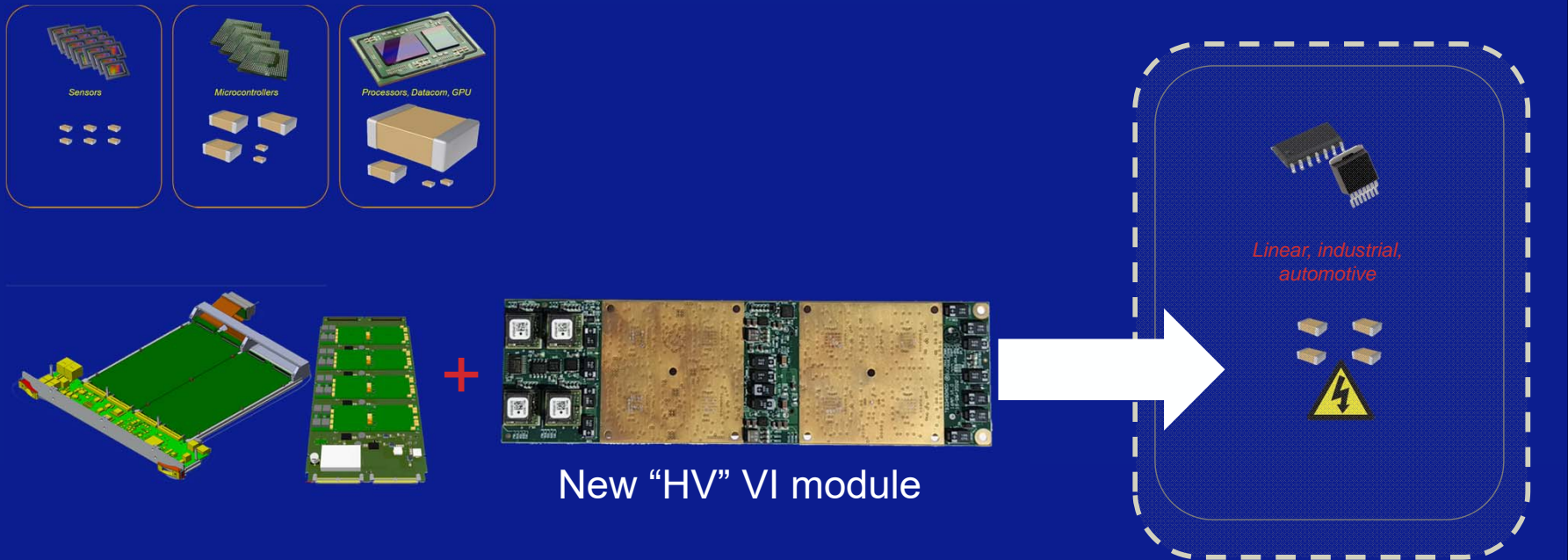


Implemented solution

Measurements, dynamic behaviour, cost analysis has driven to a better compromise:

- 1 GO/GI every cluster of 4 channels
- Local 8x8 Crosspoint with 8 x 8, 500MHz
- Maximum 2 Xpoint level

Moving Forward



Summary & Closing

- Single DPS instrument that is scalable, flexible and gang-able from low to high power 1A to 128A per instrument.
- Instrument maintains dynamic performance in all configurations.
- FPGA flexibility for application specific requirements.
- Provides scale to enable high performance cost effective DUT power solutions.



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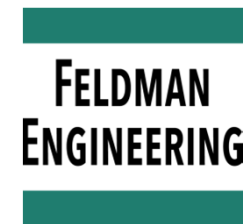


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